



## Material Content Data Sheet



<b>Sales Product Name</b>		TLF1963TB		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000994124						
<b>Package</b>		PG-TO263-5-1		<b>Weight*</b>		1672.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.428	0.26	0.26	2647	2647
leadframe	inorganic material	phosphorus	7723-14-0	0.145	0.01		87	
	non noble metal	iron	7439-89-6	0.483	0.03		289	
	non noble metal	copper	7440-50-8	482.096	28.82	28.86	288172	288548
	non noble metal	aluminium	7429-90-5	0.258	0.02	0.02	154	154
wire	non noble metal	aluminium	7429-90-5	0.258	0.02	0.02	154	154
encapsulation	organic material	carbon black	1333-86-4	1.455	0.09		869	
	plastics	epoxy resin	-	66.908	4.00		39994	
	inorganic material	silicondioxide	60676-86-0	658.898	39.37	43.46	393855	434718
leadfinish	non noble metal	tin	7440-31-5	12.370	0.74	0.74	7394	7394
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.243	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.073	0.00		43	
	noble metal	silver	7440-22-4	0.091	0.01		54	
	non noble metal	lead	7439-92-1	3.470	0.21	0.22	2074	2171
heatspreader	inorganic material	phosphorus	7723-14-0	0.133	0.01		79	
	non noble metal	iron	7439-89-6	0.442	0.03		264	
	non noble metal	copper	7440-50-8	441.456	26.39	26.43	263879	264222
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com